E-Beam

- 1. Mount up to 4 wafers to the stage using screws with washers. Use care to not over-tighten the screws as this can cause cracks in the wafer
- 2. Set Ti crucible to active using the hearth controller
- 3. Press the big red button to vent the chamber
- 4. Once the pressure reaches atmospheric ($\sim 7.6 \times 10^2$ torr), unlatch and open the door
- 5. Mount the stage to the ceiling of the E-BEAM evaporation chamber with the center screw
- 6. Check the level of titanium in the crucible. If needed, add more pellets (the crucible should be between $\frac{1}{2}$ and $\frac{2}{3}$ full). Do not overfill, as this can cause the rotating hearth to jam.
- 7. Vacuum any loose debris from the floor of the chamber, as well as around the O-ring and the door mating surface
- 8. Clean the O-ring with isopropanol and a cleanroom wipe, as well as the door mating surface
- 9. Shut the door and latch shut (\sim finger tight)
- 10. Press the big green button to begin venting down the chamber
- 11. Wait 3-5 hours or until the chamber reaches a pressure of $\sim 1.0 \times 10^{-6}$ torr
- 12. Turn on main power switches
- 13. Turn main power key to on
- 14. Wait \sim 10 seconds for fans and relays to turn on
- 15. Press main power reset, then main power on
- 16. Sweep select on
- 17. Select titanium film on main controller screen
- 18. Press start. The screen should show 'ready'
- 19. Press start once more
- 20. Press manual mode
- 21. Open the E-Gun shutter
- 22. Using the hand controller, set power to 3.1-3.3%
- 23. Wait for the titanium to heat. When the evaporation rate passes ~ 1.0 Å/sec, open the sample shutter and reset the evaporation counter simultaneously
- 24. Deposit 400Å of titanium, keeping the evaporation rate between 1.0-2.0 Å/sec
- 25. Once \sim 400Å of titanium has been deposited, press stop and close the sample shutter simultaneously.
- 26. Close the E-gun shutter
- 27. Turn off the sweep controller
- 28. Main power off, main power key off
- 29. Turn off main power switches
- 30. Press the big red button to vent the chamber
- 31. Once the pressure reaches atmospheric ($\sim 7.6 \times 10^2 \text{ torr}$), unlatch and open the door
- 32. Remove the stage with attached wafers
- 33. Vacuum any loose debris from the floor of the chamber, as well as around the O-ring and the door mating surface
- 34. Clean the O-ring with isopropanol and a cleanroom wipe, as well as the door mating surface
- 35. Shut the door and latch shut (\sim finger tight)
- 36. Press the big green button to begin pressuring down the chamber
- 37. Remove wafers from the stage, and place screws & washers in correct storage bin

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